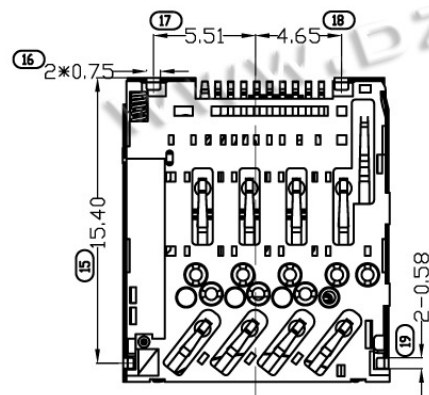
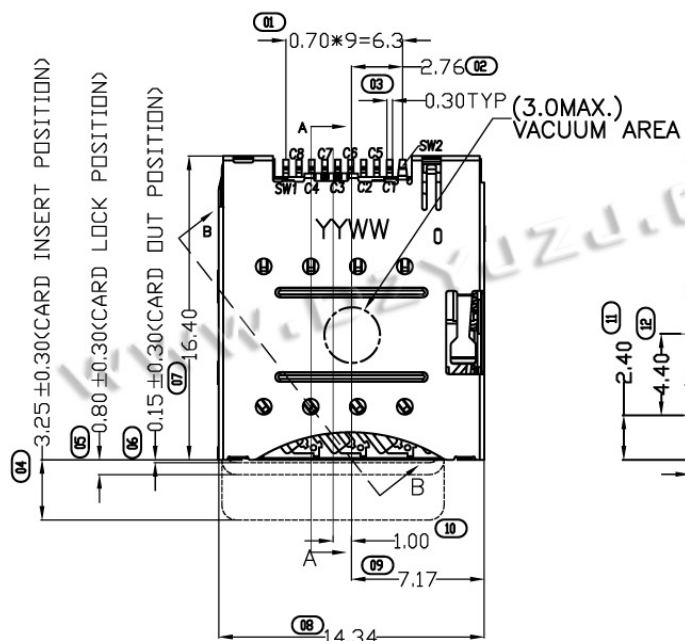
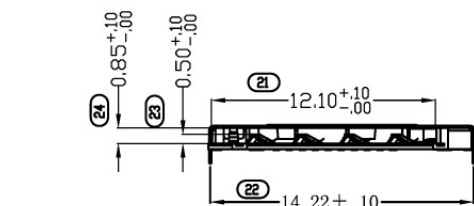


NOTES:

MATERIAL:

Insulator: High Temperature Thermoplastic,
UL 94V-0.

Contact: Copper Alloy

Shell: STAINLESS

PLATING:

TERMINAL:

CONTACT AREA: GOLD OR NICKEL.

SOLDER AREA: MATTE TIN 80U" PLATED.

SHELL: GOLD OR NICKEL.

SOLDER AREA: GOLD PLATED.

Electrical:

Current Rating :1A max.

Voltage Rating :30V DC MAX

Ambient Temperature Range :-20°C~+85°C

Storage Temperature Range :-40°C~+85°C

Ambient Humidity Range :95% R.H. Max.

Contact Resistance:100mΩ maxΩ

Insulation Resistance:1000M min./500V DC

Dielectric Withstanding Voltage:500V AC

Mating Cycles:5,000 Insertions

Temperature: 260°C ±5°



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TOLERANCE:

X.X ±0.30

X.XX ±0.25

X.XXX ±0.15

X' ±2° X.X' ±0.5°

UNIT: mm [inch]

SCALE:1:1 SIZE: A4

DRAWN BY:

陈一鸣

DATE:

2014-02-23

PART NAME:

MICRO SIM PUSH 1.3H DIP型防渍P

CHECKED BY:

马跃

DATE:

2014-02-23

PART NO.

HYC266-SIM10-130

MOLD NO.

HYC-SIM201029117

APPROVED BY:

邱国夷

DATE:

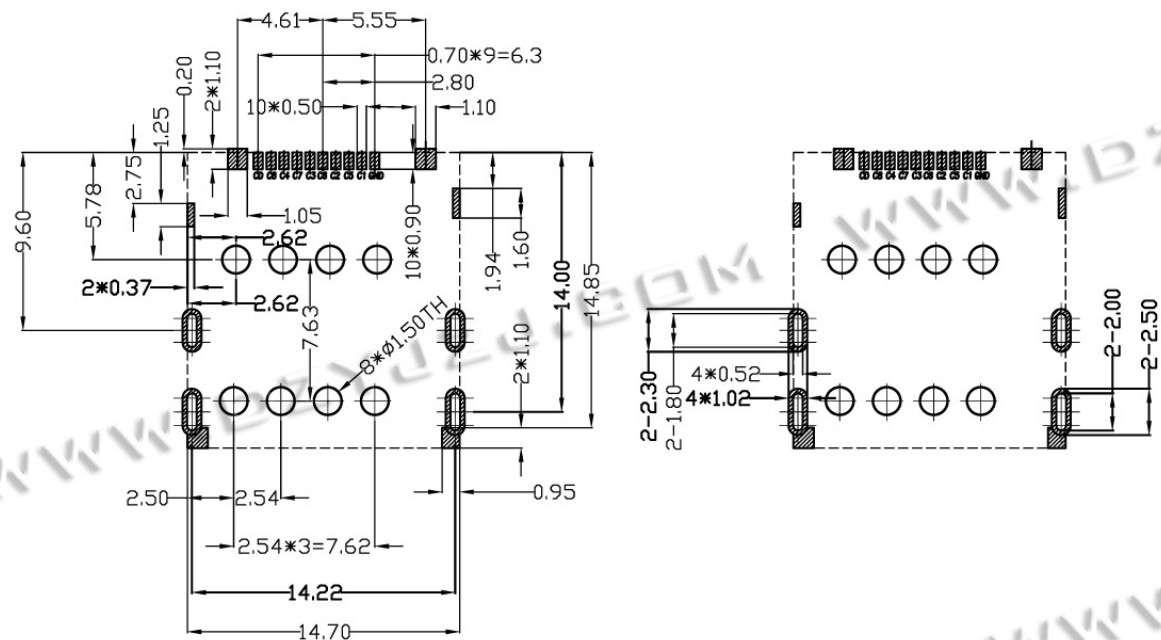
2014-02-23

DRAW NO:

HYC-SIM201029117

SHEET NO.

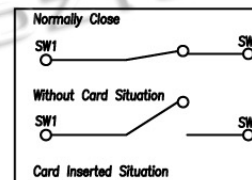
1 OF 1



□: NO WIRING AREA
■: BOARD PAD
○: PCB through hole

Figure 5.2 RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ± 0.05



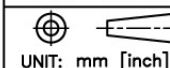
SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved
SW1	C/D
SW2	GND

NOTE 1:
After inserting the card, the terminal head will reveal the outer surface of the product, and the PCB will need to be opened to avoid the terminal.



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TOLERANCE:
X.X ± 0.30
X.XX ± 0.25
X.XXX ± 0.15
X' $\pm 2'$ X.X' $\pm 0.5'$



UNIT: mm [inch]

SCALE: 1:1 SIZE: A4

DRAWN BY :
陈一鸣

DATE :
2014-02-23

PART NAME:
MICRO SIM PUSH 1.3H DIP型防泼P

CHECKED BY:
马跃

DATE :
2014-02-23

PART NO. HYC266-SIM10-130

APPROVED BY:
邱国夷

DATE :
2014-02-23

DRAW NO: HYC-SIM201029117

SHEET NO. 1 OF 1